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(54) Title: SUPPORT SYSTEM FOR A SEMICONDUCTOR DEVICE

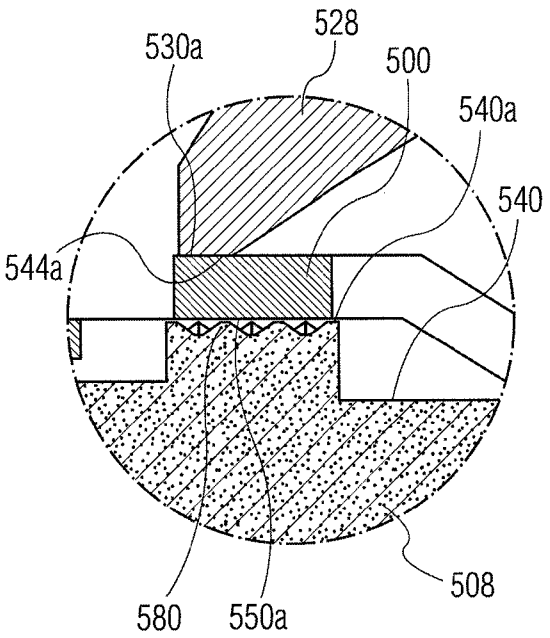


FIG. 5B

(57) Abstract: A support system for a semiconductor device during a wire or ribbon bonding operation is provided. The support system includes a body portion defining an upper surface. The upper surface has an upper surface contact region configured to support at least a portion of a lower surface of a semiconductor device at a lower surface contact region during a wire or ribbon bonding operation. The support system also includes a plurality of protrusions on the upper surface contact region.

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